

Parameter	Ratings	Units
Load Voltage, AC/DC	250	V <sub>P</sub>
Load Current	250	mA <sub>rms</sub> / mA <sub>DC</sub>
On-Resistance (max)	7	Ω

### Features

- 3750V<sub>rms</sub> Input/Output Isolation
- Low Drive Power Requirements
- High Reliability
- No EMI/RFI Generation
- Small 8-Pin Package
- Flammability Rating UL 94 V-0
- Surface Mount, Tape & Reel Versions Available

### Applications

- Telecommunications
- Instrumentation
- Multiplexers
- Data Acquisition
- Electronic Switching
- I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Industrial Controls

### Description

PBB150 is a dual single-pole, normally closed (1-Form-B) solid state relay comprising two independently controlled, optically coupled MOSFET switches that use optically coupled MOSFET technology to provide 3750V<sub>rms</sub> of input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient infrared LED.

Dual single-pole OptoMOS relays provide a more compact design solution than discrete single-pole relays in a variety of applications by incorporating both relays in a single 8-pin package.

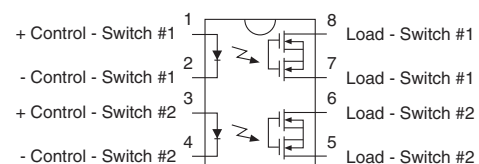
### Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 62368-1 Certified Component: TUV Certificate B 082667 0008

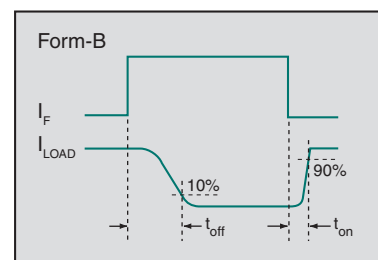
### Ordering Information

Part #	Description
PBB150	8-Pin DIP (50/Tube)
PBB150P	8-Pin (Flatpack) (50/Tube)
PBB150PTR	8-Pin (Flatpack) (1000/Reel)
PBB150S	8-Pin Surface Mount (50/Tube)
PBB150STR	8-Pin Surface Mount (1,000/Reel)

### Pin Configuration



### Switching Characteristics of Normally Closed Devices



### Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	250	$V_P$
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation <sup>1</sup>	150	mW
Total Power Dissipation <sup>2</sup>	800	mW
Isolation Voltage, Input to Output	3750	$V_{rms}$
Operational Temperature, Ambient	-40 to +85	°C
Storage Temperature	-40 to +125	°C

<sup>1</sup> Derate linearly 1.33 mW / °C

<sup>2</sup> Derate linearly 6.67 mW / °C

*Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.*

*Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.*

### Electrical Characteristics @ 25°C

Parameter	Conditions	Symbol	Min	Typ	Max	Units
<b>Output Characteristics</b>						
Blocking Voltage	$I_L=1\mu A$	$V_{DRM}$	250	-	-	$V_P$
Load Current, AC/DC						
Continuous <sup>1</sup>	-	$I_L$	-	-	250	$mA_{rms} / mA_{DC}$
Peak	10ms	$I_{LPK}$	-	-	±500	$mA_P$
On-Resistance	$I_L=250mA$	$R_{ON}$	-	-	7	$\Omega$
Off-State Leakage Current	$V_L=250V_P$	$I_{LEAK}$	-	-	1	$\mu A$
<b>Switching Speeds</b>						
Turn-On	$I_F=5mA, V_L=10V$	$t_{on}$	-	-	2.5	ms
Turn-Off		$t_{off}$	-	-	2.5	
Output Capacitance	$I_F=5mA, V_L=50V, f=1MHz$	$C_{OUT}$	-	110	-	pF
<b>Input Characteristics</b>						
Input Control Current to Activate	$I_L=250mA$	$I_F$	-	-	5	mA
Input Control Current to Deactivate	-	$I_F$	0.4	0.7	-	mA
Input Voltage Drop	$I_F=5mA$	$V_F$	0.9	1.35	1.5	V
Reverse Input Current	$V_R=5V$	$I_R$	-	-	10	$\mu A$
<b>Common Characteristics</b>						
Input to Output Capacitance	$V_{IO}=0V, f=1MHz$	$C_{IO}$	-	3	-	pF

<sup>1</sup> If both poles operate simultaneously, then the load current must be derated in order not to exceed the package power dissipation value.

## Manufacturing Information

### Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL)** classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
PBB150S	MSL 1
PBB150P	MSL 3

### ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard **JESD-625**.

### Soldering Profile

Provided in the table below is the **IPC/JEDEC J-STD-020** Classification Temperature ( $T_C$ ) and the maximum total dwell time ( $t_p$ ) in all reflow processes that the body temperature of these surface mount devices may be ( $T_C - 5$ )°C or greater. The device's body temperature must not exceed the Classification Temperature at any time during reflow soldering processes.

Device	Classification Temperature ( $T_C$ )	Dwell Time ( $t_p$ )	Max Reflow Cycles
PBB150S	250°C	30 seconds	3
PBB150P	245°C	30 seconds	3

For through-hole devices, the maximum solder temperature and the maximum total dwell time in all solder waves that the device pins (leads) may be at the maximum solder temperature is given in the table below. The body temperature of the device must not exceed the Max Body Temperature shown below at any time during the soldering process.

Device	Max Solder Temperature	Max Body Temperature	Max Total Dwell Time	Wave Cycles
PBB150	260°C	250°C	10 seconds	1

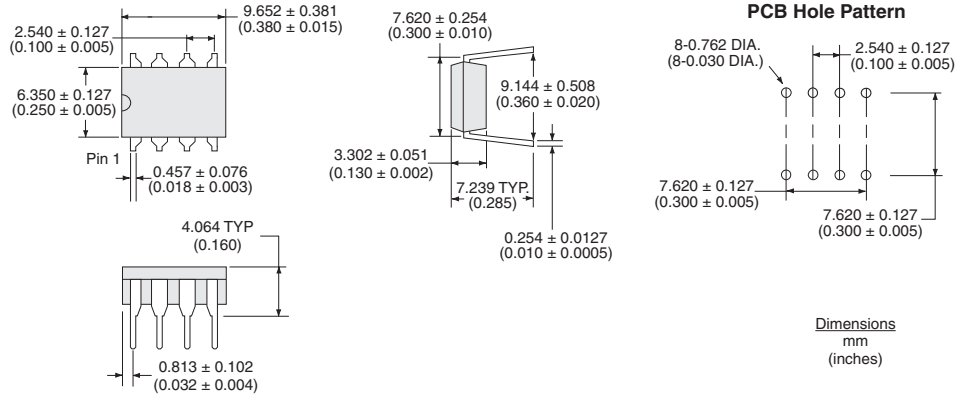
### Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to halide flux or solvents.

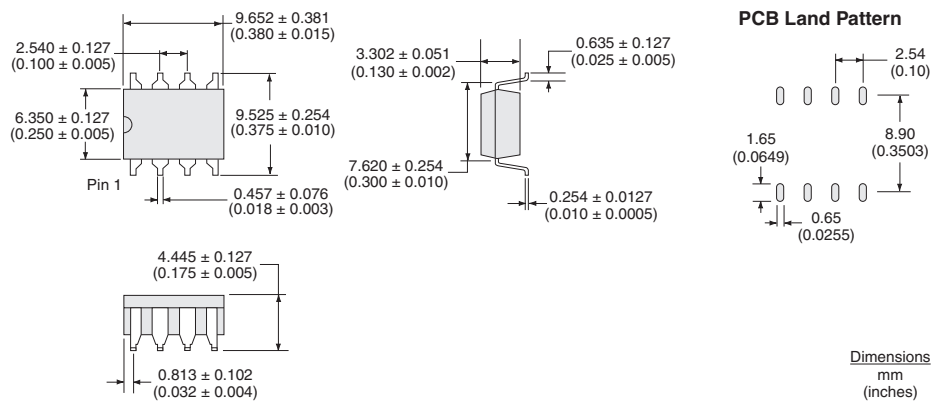


**Mechanical Dimensions**

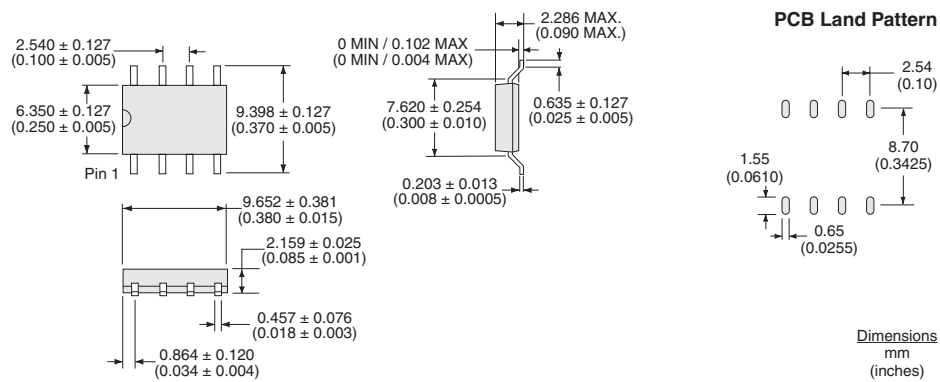
**PBB150**



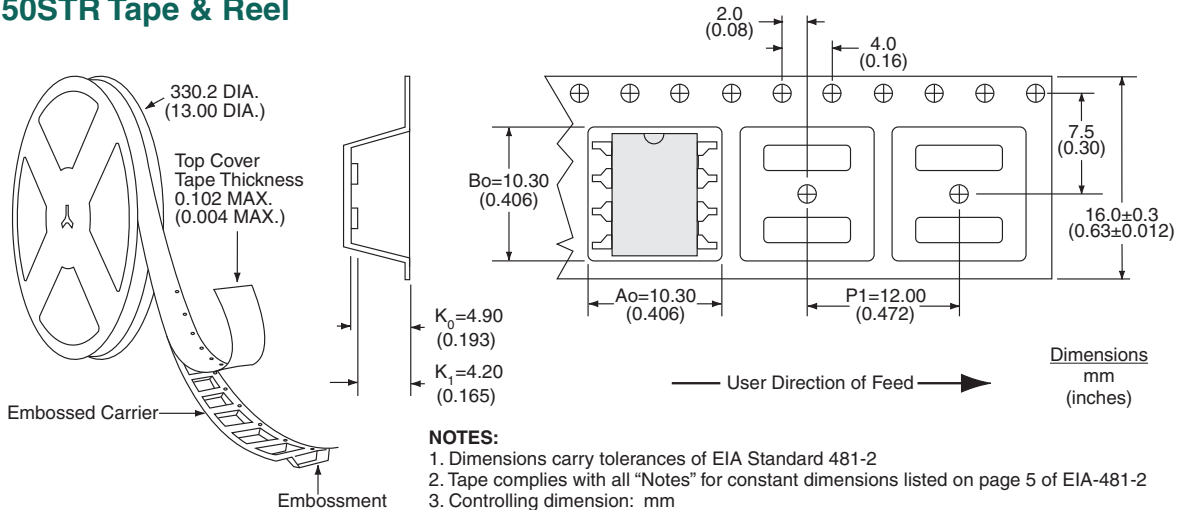
**PBB150S**



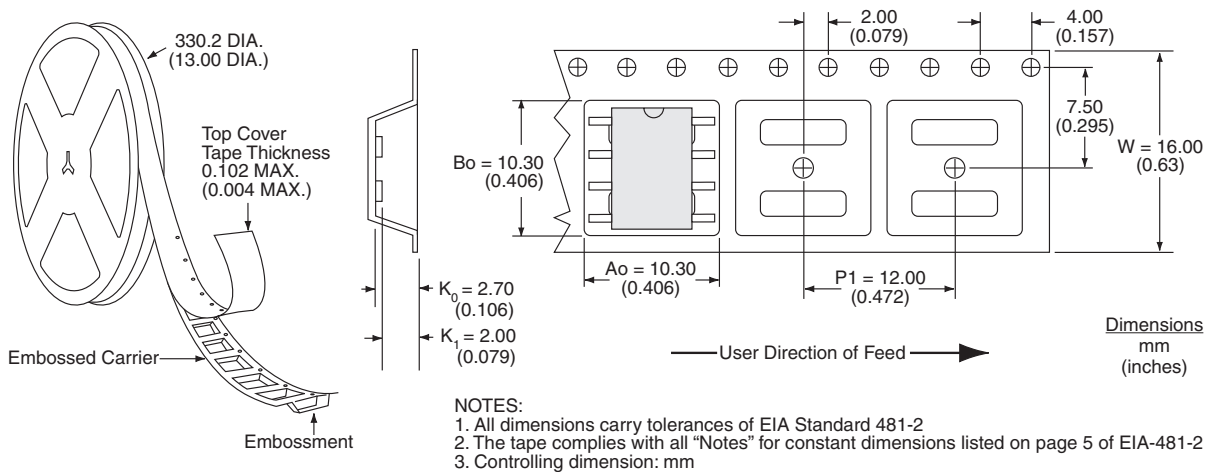
**PBB150P**



### PBB150STR Tape & Reel



### PBB150PTR Tape & Reel



For additional information please visit our website at: <https://www.ixysic.com>